

ABSTRACT OF THE DISCLOSURE

The present invention relates to a substrate assembling apparatus in which substrates to be bonded together in a vacuum chamber are held opposite to each other and bonded together by narrowing the gap between the
5 substrates in a vacuum.

In the substrate assembling apparatus in accordance with the present invention, a pressing plate comprises a means for holding an upper substrate out of the substrates
10 opposite to each other by making an electrostatic attractive force act on the upper substrate in the vacuum chamber, and the upper and the lower substrates are bonded to each other in a vacuum chamber by narrowing the gap between the substrates in a vacuum while the upper
15 substrate is being held using the holding means.

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